BCP 54 / 55 / 56

NPN SILICON PLANAR MEDIUM POWER TRANSISTORS IN SOT223

Features

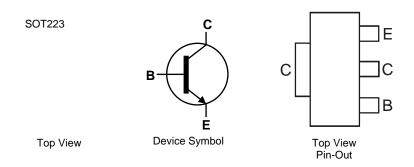
- I_C = 1A Continuous Collector Current
- Low Saturation Voltage V_{CE(sat)} < 500mV @ 0.5A
- Gain groups 10 and 16
- Epitaxial Planar Die Construction
- Complementary PNP types: BCP51, 52 and 53
- Lead-Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Devices (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound (Note 2)
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: 0.112 grams (Approximate)

Applications

- Medium Power Switching or Amplification Applications
- AF driver and output stages



Ordering Information (Note 3)

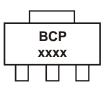
Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BCP54TA	BCP 54	7	12	1,000
BCP5410TA	BCP 5410	7	12	1,000
BCP5416TA	BCP 5416	7	12	1,000
BCP55TA	BCP 55	7	12	1,000
BCP5510TA	BCP 5510	7	12	1,000
BCP5516TA	BCP 5516	7	12	1,000
BCP56TA	BCP 56	7	12	1,000
BCP5610TA	BCP 5610	7	12	1,000
BCP5616TA	BCP 5616	7	12	1,000
BCP5616TC	BCP 5616	13	12	4,000

Notes: 1. No purposefully added lead.

2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com

3. For packaging details, go to our website http://www.diodes.com

Marking Information



BCP = Product Type Marking Code, Line 1. XXXX = Product Type Marking Code, Line 2 as follows:

BCP54 = 54	BCP55 = 55	BCP56 = 56
BCP5410 = 5410	BCP5510 = 5510	BCP5610 = 5610
BCP5416 = 5416	BCP5516 = 5516	BCP5616 = 5616

Maximum Ratings @ $T_A = 25$ °C unless otherwise specified

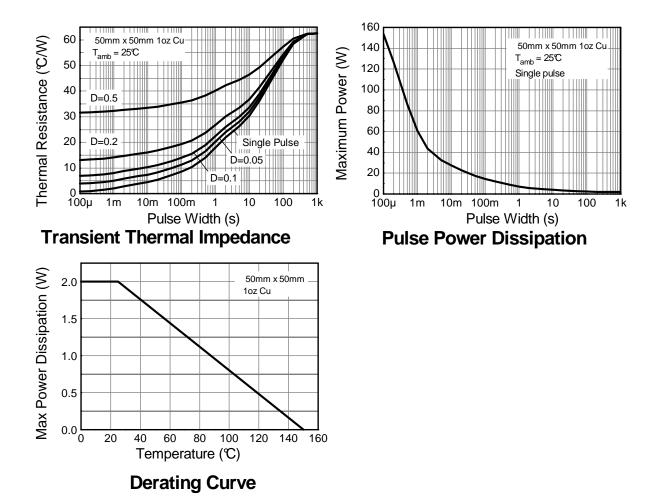
Characteristic	Symbol	BCP54	BCP55	BCP56	Unit
Collector-Base Voltage	V _{CBO}	45	60	100	V
Collector-Emitter Voltage	V _{CEO}	45	60	80	V
Emitter-Base Voltage	V _{EBO}	5			V
Continuous Collector Current	Ι _C	1			٨
Peak Pulse Collector Current	I _{CM}	2			A
Continuous Base Current	IB	100			m (
Peak Pulse Base Current	I _{BM}		mA		

Thermal Characteristics @ TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	PD	2	W
Thermal Resistance, Junction to Ambient (Note 4)	R _{θJA}	62	°C/W
Thermal Resistance, Junction to Leads (Note 5)	R _{θJL}	19.4	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-65 to +150	°C

Notes: 4. For a device surface mounted on 50mm X 50mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions; the device is measured when operating in a steady-state condition.5. Thermal resistance from junction to solder-point (at the end of the collector lead).

Thermal Characteristics

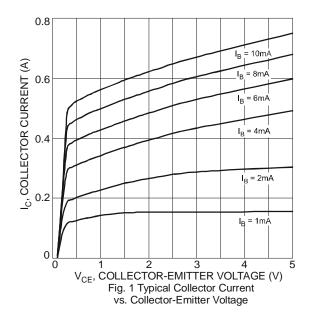


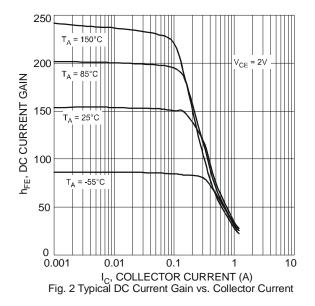
BCP 54 / 55 / 56 Datasheet Number: DS35367 Rev. 2 – 2

Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BCP54 BCP55 BCP56	BV _{CBO}	45 60 100	-	-	V	I _C = 100μΑ
Collector-Emitter Breakdown Voltage (Note 6)	BCP54 BCP55 BCP56	BV _{CEO}	45 60 80	-	-	V	I _C = 10mA
Emitter-Base Breakdown Voltage		BV _{EBO}	5	-	-	V	I _E = 10μΑ
Collector Cut-off Current		I _{CBO}	-	-	0.1 20	μA	V _{CB} = 30V V _{CB} = 30V, T _A = 150℃
Emitter Cut-off Current		I _{EBO}	-	-	20	nA	$V_{EB} = 4V$
Static Forward Current Transfer Ratio (Note 6)	All versions	h _{FE}	25 40 25 63 100	- - -	- 250 - 160 250		$\begin{array}{l} I_{c} = 5mA, \ V_{CE} = 2V \\ I_{c} = 150mA, \ V_{CE} = 2V \\ I_{c} = 500mA, \ V_{CE} = 2V \\ \hline I_{c} = 150mA, \ V_{CE} = 2V \\ \hline I_{c} = 150mA, \ V_{CE} = 2V \\ \hline \end{array}$
Collector-Emitter Saturation Voltage (Note 6)		V _{CE(sat)}	-	-	0.5	V	$I_{\rm C} = 150 \text{mA}, V_{\rm CE} = 2 \text{V}$ $I_{\rm C} = 500 \text{mA}, I_{\rm B} = 50 \text{mA}$
Base-Emitter Turn-On Voltage (Note 6)		V _{BE(on)}	-	-	1.0	V	$I_{\rm C} = 500 \text{mA}, V_{\rm CE} = 2V$
Transition Frequency		f⊤	150	-	-	MHz	$I_{C} = 50 \text{mA}, V_{CE} = 10 \text{V}$ f = 100MHz
Output Capacitance		Cobo	-	-	25	pF	$V_{CB} = 10V, f = 1MHz$

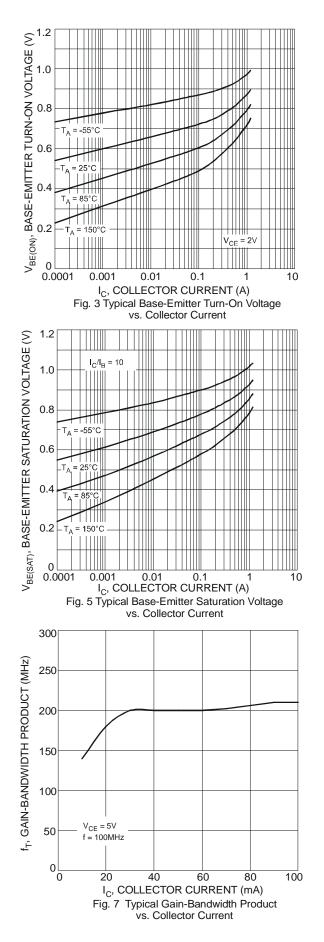
Electrical Characteristics @ T_A = 25°C unless otherwise specified

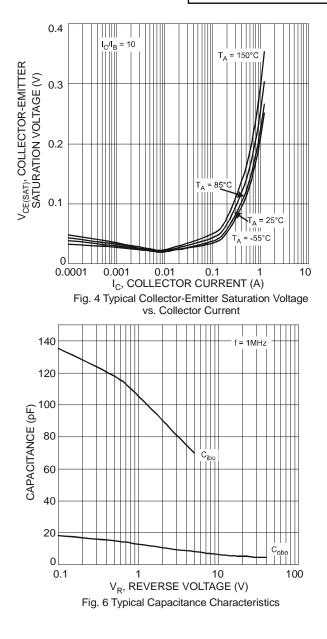
Notes: 6. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.



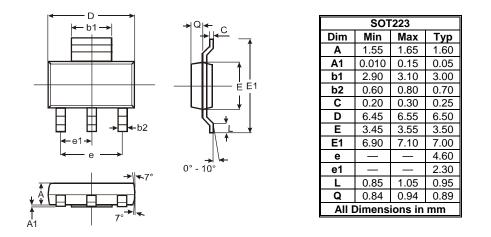


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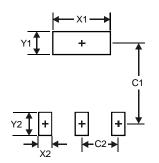




Package Outline Dimensions



Suggested Pad Layout



Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3

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